

## Features

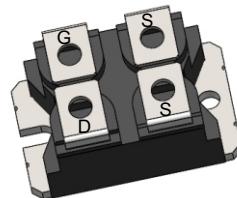
38N100S7P, the silicon N-channel Enhanced VDMOSFET, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is SOT-227, which accords with the RoHS standard.

Product Summary			
V <sub>DS</sub>	R <sub>D(on)</sub> (mΩ)Typ	I <sub>D</sub> (A)	Q <sub>g</sub> (Max)
1000V	196 @ 10V 18A	38	308nc

SOT-227

## Features

- Fast switching
- ESD Improved Capability
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test



## Mechanical Data

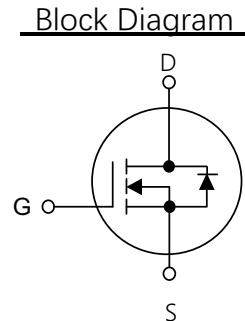
- Case:SOT-227 Package

## Application

- Power switch circuit of POWER

Pin Definition:

- G. Gate  
D. Drain  
S. Source


 Table1 Absolute Maximum Ratings (T<sub>c</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	1000	V
Gate-Source Voltage	V <sub>GS</sub>	±40	V
Continuous Drain Current	I <sub>D</sub>	38	A
T <sub>c</sub> =100°C		30	
Pulsed Drain Current (Note 1)	I <sub>DM</sub>	152	A
Power Dissipation T <sub>c</sub> =25°C	P <sub>D</sub>	890	W
Single Pulse Avalanche Energy(Note 2)	E <sub>AS</sub>	5000	mJ
Avalanche Current(Note 1)	I <sub>AR</sub>	38	A
Operating Junction and Storage Temperature	T <sub>J</sub> /T <sub>STG</sub>	-55~+150	°C

**Table 2.Thermal Characteristics**

Parameter	Symbol	SOT-227	Unit
Thermal resistance Case to heatsink	R <sub>θCS</sub>	0.05	°C/W
Thermal resistance Junction to Case	R <sub>θJC</sub>	0.14	°C/W

**Table 3. Electrical Characteristics (T<sub>j</sub>=25°C, unless otherwise specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V,I <sub>D</sub> =250μA	1000	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =1000V,V <sub>GS</sub> =0V	-	-	1.0	μA
Gate- Source Leakage Current	Forward	I <sub>GSS</sub>	V <sub>GS</sub> =30V,V <sub>DS</sub> =0V	-	-	100 nA
	Reverse		V <sub>GS</sub> =-30V,V <sub>DS</sub> =0V	-	-	-100 nA
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	3.0	-	5.5	V
Static Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V,I <sub>D</sub> =18A	-	196	280	mΩ
Forward Trans conductance	g <sub>f</sub>	V <sub>DS</sub> =15V,I <sub>D</sub> =40A	-	50	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V,f=1MHz	-	19	-	nF
Output Capacitance	C <sub>oss</sub>		-	1012	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	520	-	pF
<b>Switching Characteristics</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =500V,I <sub>D</sub> =19A V <sub>GS</sub> =10V,R <sub>G</sub> =25Ω,	-	30	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	30	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	60	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	35	-	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> =500V,I <sub>D</sub> =18A, V <sub>GS</sub> =10V	-	308	-	nC
Gate-Source Charge	Q <sub>GS</sub>		-	107	-	nC
Gate-Drain Charge	Q <sub>GD</sub>		-	64	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b> (Note 3)						
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>s</sub> =38A	-	-	1.5	V
Maximum Continuous Drain-Source Diode Forward Current	I <sub>s</sub>		-	-	38	A
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> =0V,I <sub>s</sub> =38A dI <sub>f</sub> /dt=100A/μs		500		ns
Reverse Recovery Charge	Q <sub>RR</sub>			3.8		μC

Notes: 1 RepetitiveRating Pulse width limited by maximum junction temperature

 2 I<sub>SD</sub>=38A,V<sub>DD</sub>≤BV<sub>DS</sub>,di/dt≤100A/μs,Starting TJ=25°C

3 Pulse Test: Pulse width ≤300μs,Duty cycle≤2%

## Typical Characteristics Diagrams

Figure 1. Output Characteristics

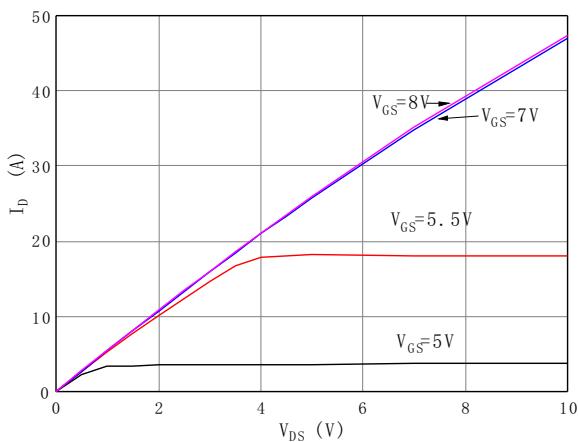


Figure 2. Normalized  $R_{DS(ON)}$  vs Temperature

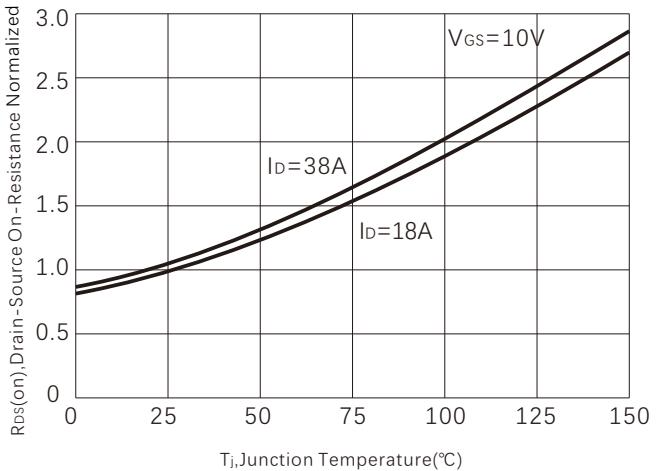


Figure 3. On-Resistance to  $ID=18A$  vs. Drain Current

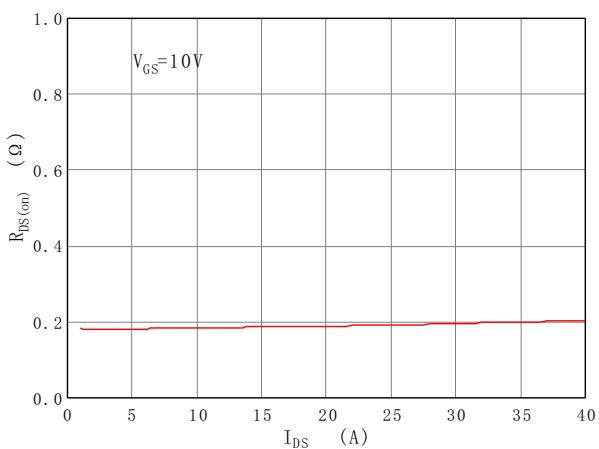


Figure 4. Capacitance

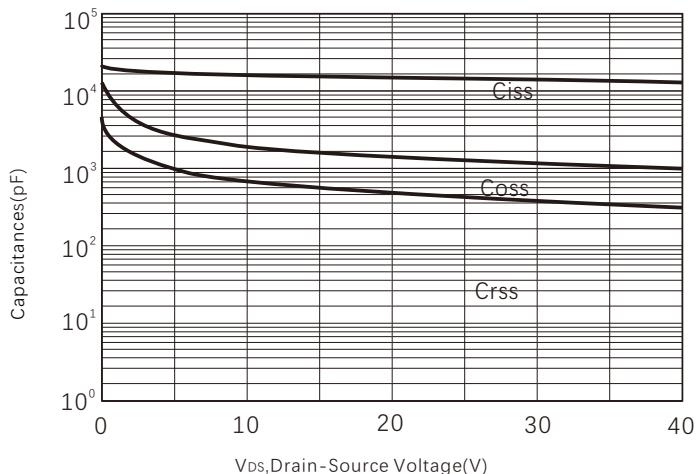


Figure 5. Gate charge

$Q_g$  随  $V_d$  变化图

测试条件— $I_d: 18.00A, I_g: 1.00mA, V_{gon}: 10.0V, V_d: 500.0V \sim 600.0V$

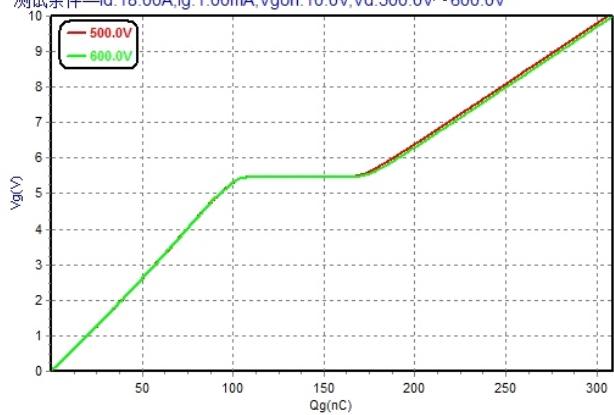


Figure 6. Source-Drain Diode Forward Voltage

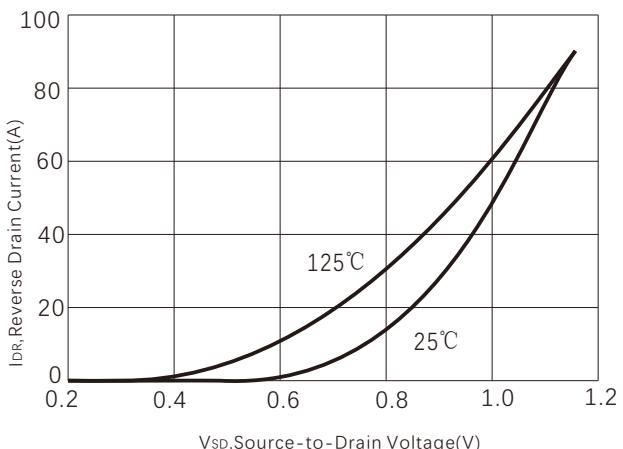


Figure 7. Maximum Drain Current vs Temperature

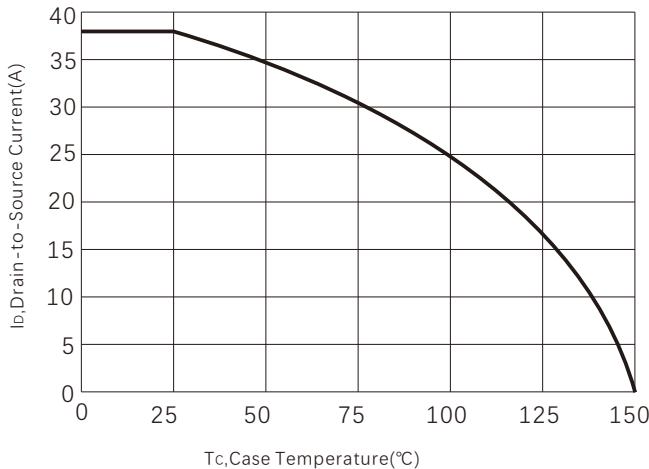


Figure 8. Transfer Characteristics

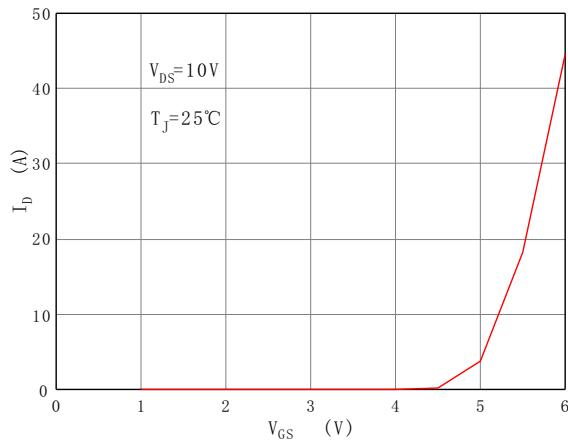


Figure 9. Safe operating area

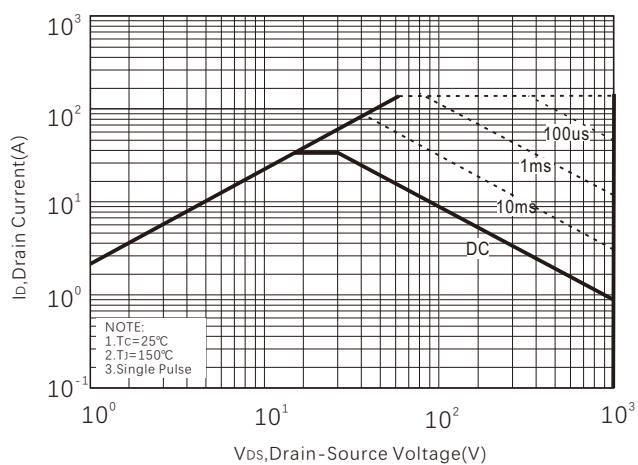
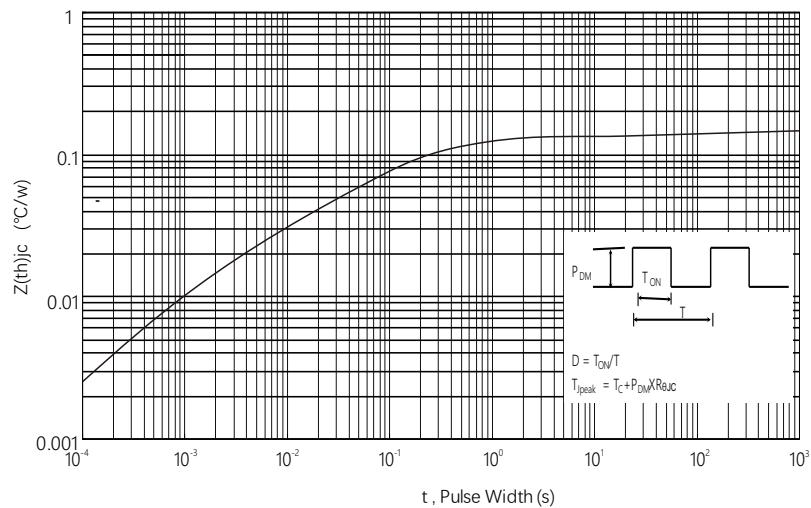
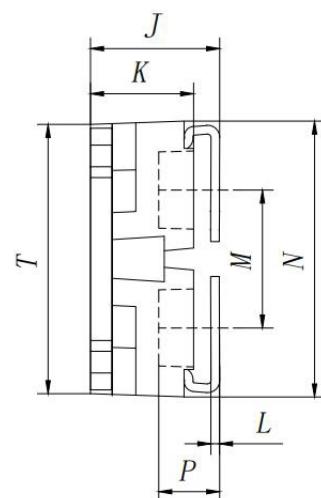
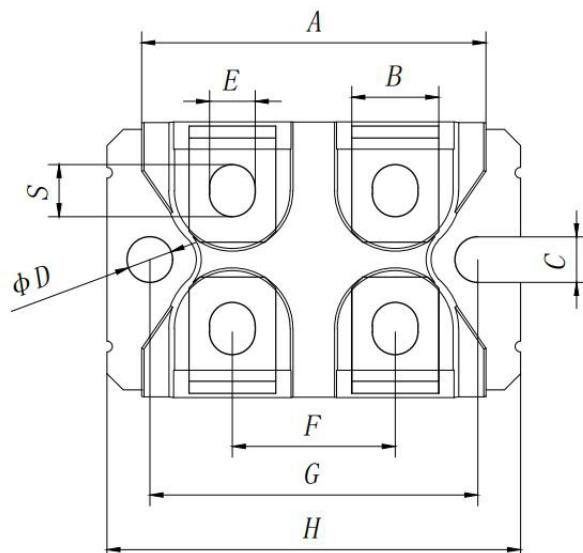
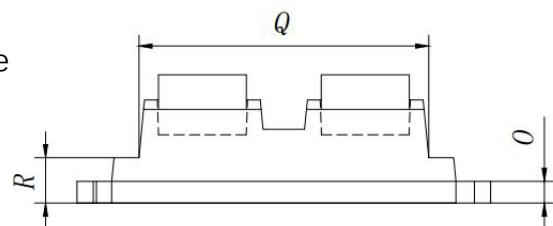


Figure 10. Maximum Transient Thermal Impedance



## Dimensions

SOT-227package



SYMBOLS	DIMENSION IN MM		
	MIN	NOM	MAX
A	31.20	31.70	32.20
B	7.50	8.00	8.50
C	3.80	4.20	4.60
D	3.80	4.20	4.60
E	3.80	4.20	4.60
F	14.50	15.00	15.50
G	29.80	30.20	30.60
H	37.70	38.10	38.50
J	11.50	11.90	12.30
K	8.90	9.50	10.00
L	0.75	0.80	0.85
M	12.40	12.70	13.00
N	25.00	25.40	25.80
O	1.70	2.00	2.30
P	4.95	5.60	6.10
Q	26.40	26.70	27.00
R	3.90	4.18	4.45
S	4.20	4.80	5.40
T	23.80	24.80	25.80

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